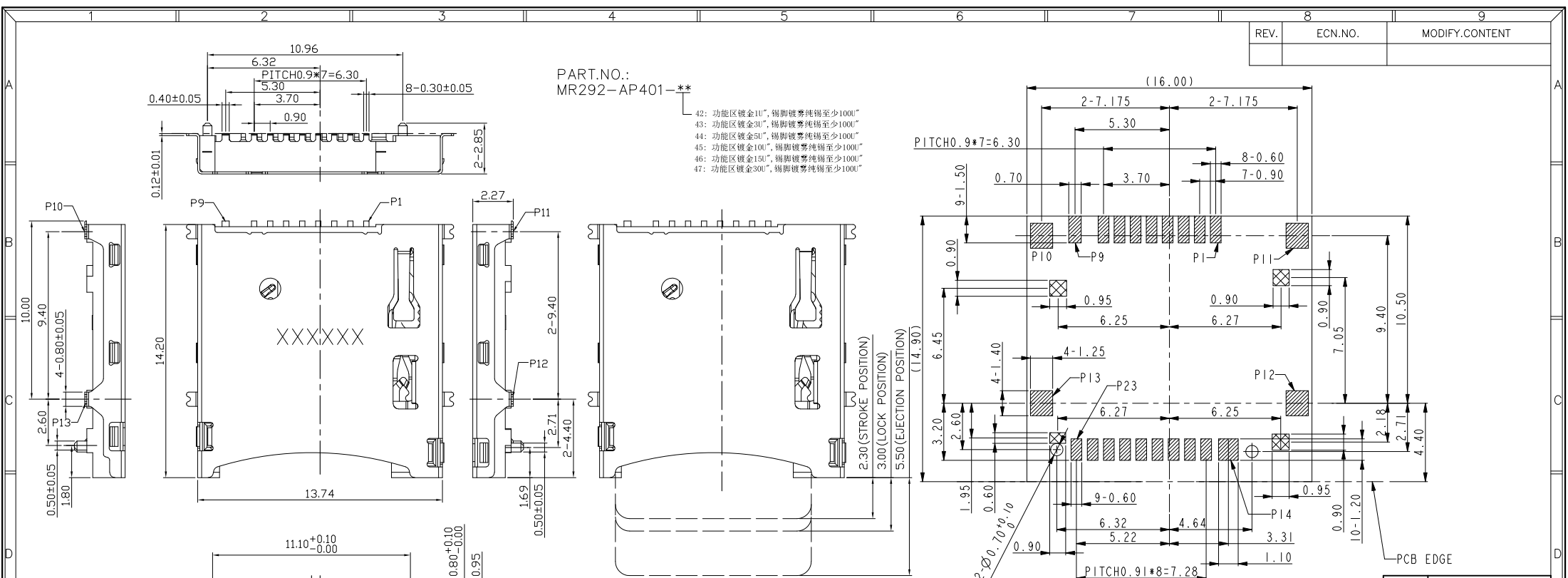


PART.NO.:  
MR292-AP401-\*\*

- 42: 功能区镀金11u", 锡脚镀弯纯锡至少100u"
- 43: 功能区镀金30", 锡脚镀弯纯锡至少100u"
- 44: 功能区镀金50", 锡脚镀弯纯锡至少100u"
- 45: 功能区镀金100", 锡脚镀弯纯锡至少100u"
- 46: 功能区镀金150", 锡脚镀弯纯锡至少100u"
- 47: 功能区镀金300", 锡脚镀弯纯锡至少100u"



NOTES :

1. MATERIAL :

- 1.1 HOUSING:LCP S475 UL94 V-0, BLACK COLOR.
- 1.2 SHELL: Stainless Steel SUS304.
- 1.3 CONTACT: Copper Alloy C5210.

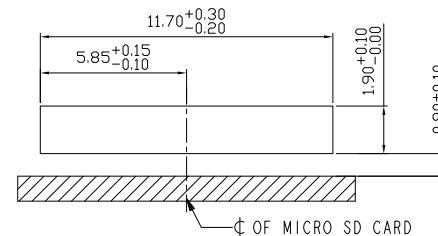
2. FINISH :

- 2.1 CONTACT: GOLD PLATING ON CONTACT AREA,  
MATTE TIN 100u"MIN ON SOLDER TAIL AREA.  
50u" MIN NICKEL PLATING OVERALL.
- 2.2 SHELL: 30u" MIN NICKEL PLATING OVERALL.

3. Electrical Characteristics:

- 3.1 Operating voltage : 100V AC(rms)/DC.
- 3.2 Current rating : 0.5 A.
- 3.3 Operating Temperature: -25°C~+85°C.
- 3.4 Contact resistance: 100 m ohms max.
- 3.5 Insulation resistance: 1000M ohms min. at 250VDC.
- 3.6 Dielectric withstanding voltage:500 VAC/1minute.

RECOMMENDED P.C.B LAYOUT  
TOP VIEW(TOLERANCE+/-0.05)



RECOMMEND ID DIMENSION

Card Detect Switch		Pin No.	Pin Assignment
Card Uninsertion	Open	PIN1	Micro SD DAT2
Card Half Insertion	Open	PIN2	Micro SD CD/DAT3
Card Insertion	Close	PIN3	Micro SD CMD
		PIN4	Micro SD VDD1
N/O	Open	PIN5	Micro SD CLK
		PIN6	Micro SD VSS
P6	Close	PIN7	Micro SD DAT0 RCLK+
		PIN8	Micro SD DAT1 PCLK-
P9	Open	PIN9	Micro SD CD
P6	Close	PIN10	GND
P9	Open	PIN11	GND
P6	Close	PIN12	GND
P9	Open	PIN13	GND
P6	Close	PIN14	GND
P9	Open	PIN15	Micro SD VDD2
P6	Close	PIN16	Micro SD SWID
P9	Open	PIN17	Micro SD VSS
P6	Close	PIN18	Micro SD D0+
P9	Open	PIN19	Micro SD D0-
P6	Close	PIN20	Micro SD VSS
P9	Open	PIN21	Micro SD D1-
P6	Close	PIN22	Micro SD D1+
P9	Open	PIN23	Micro SD VSS

GENERAL TOLERANCE		DWG.NO.	MR292-AP401-00	PART.NO.	MR292-AP401-**	DRAWN	Toff 2023.04.07
x.±0.50	x.°± 5°	REV.	A	TITLE	Micro SD6.0 Push H2.27 conn	CHECKED	
.x±0.25	.x°± 2°	SIZE	A4	SHEET	1 OF 2	APPROVED	
.xx±0.15	.xx°± 1°						